



Semiconductor | Neuromorphic A.I | IT Materials | Energy | 2^{ndary} battery

CONTENTS



ABOUT **NEPES**



BUSINESS **PORTFOLIO**



CORE **TECHNOLOGY**



GLOBAL **NEPES**



CORPORATE CULTURE



CORPORATE BRANDING



nepes' 4D management began at the very moment when the company name was chosen



4D(4th dimension) management?

The management that generate creation, innovation, pioneering and fun, satisfaction, and happiness

Corporate Identity



Trademark



Name of company nepes

Date of establishment 1990.12

Date of Listing 1999.12(KOSDAQ 033640)

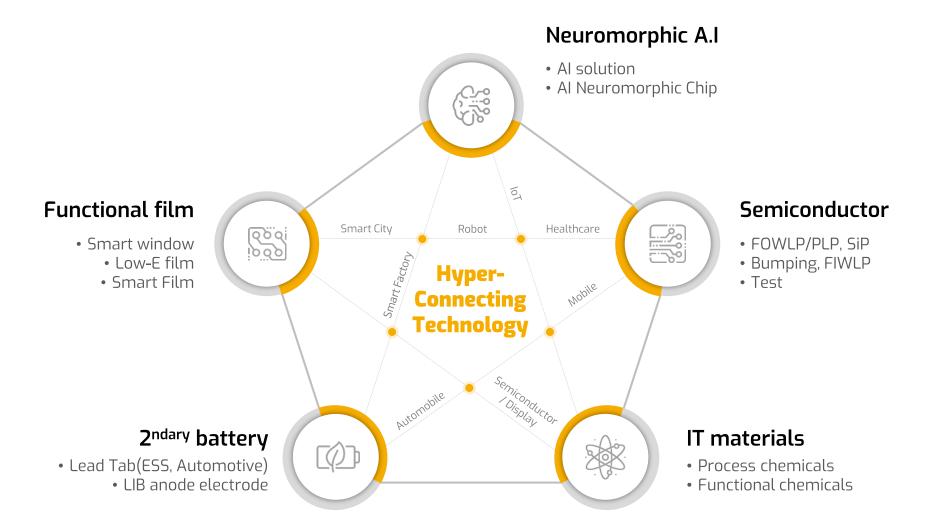
CEO Byung-Koo Lee, 李柄九)

Overseas corporation CN, US, PHL, IDN, RUS

BUSINESS PORTFOLIO



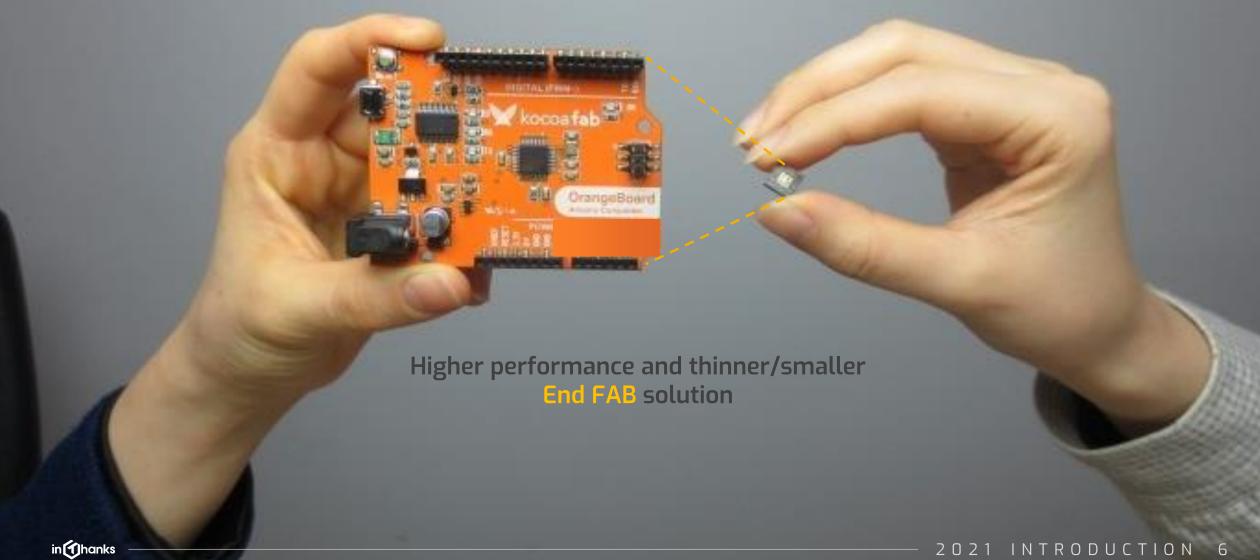
nepes makes Hyper-connecting Technology that connects future business





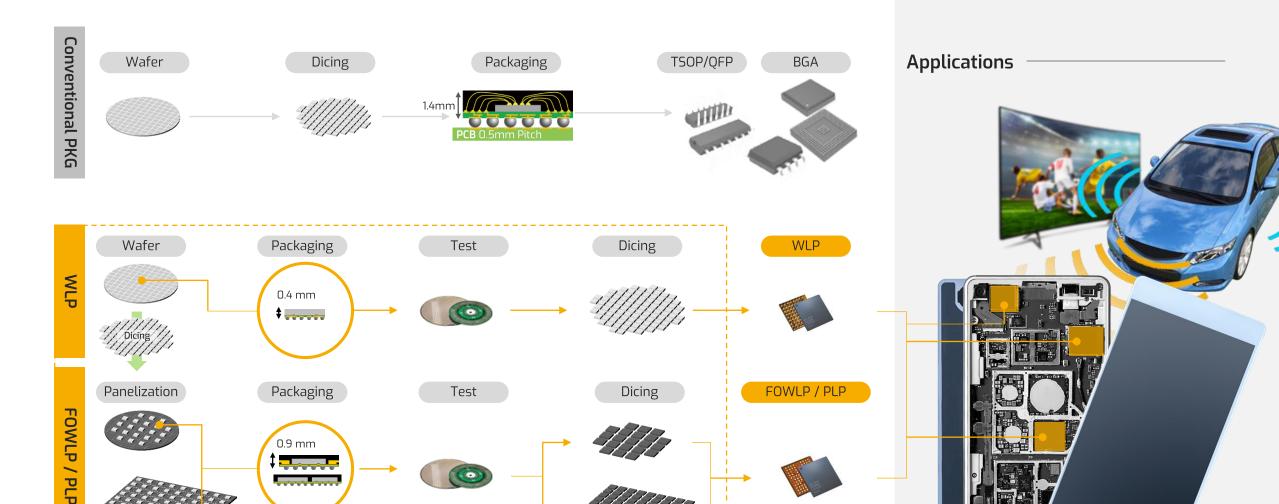






CORE TECHNOLOGY 02. Semiconductor





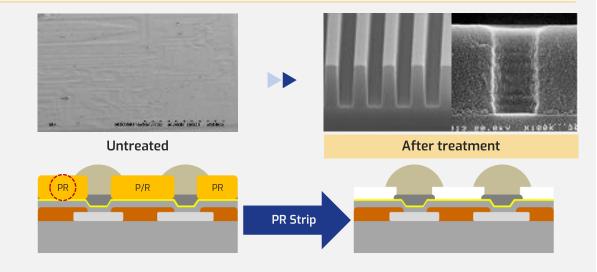


CORE TECHNOLOGY 03. IT Materials



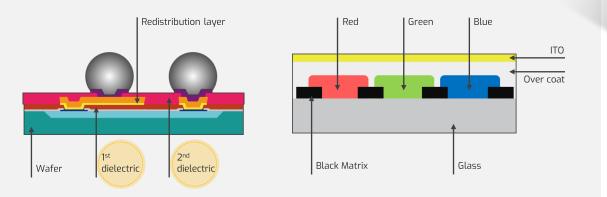
Process chemical

- PR
- Developer
- PSPI Developer
- Stripper
- Etchant
- HSN
- PV texture

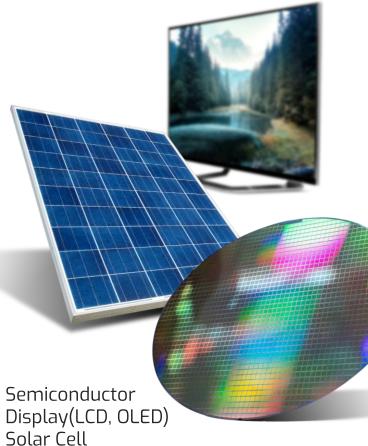


Functional chemical

- ILD
- Cu Plating
- Color paste







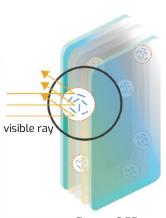




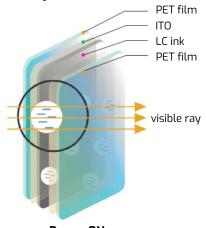




Super LC Structure and Principles



Power OFF No electric field (opaque)

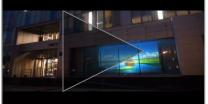


Power ON Electric field (transparent)

Service & Products

- Smart Windows(on/off)Low-E film(Pentix50, Pentix60)









Service & Applications

- Smart Sunglasses
- AR/VR glassesSwitchable Mirror
- Vehicle





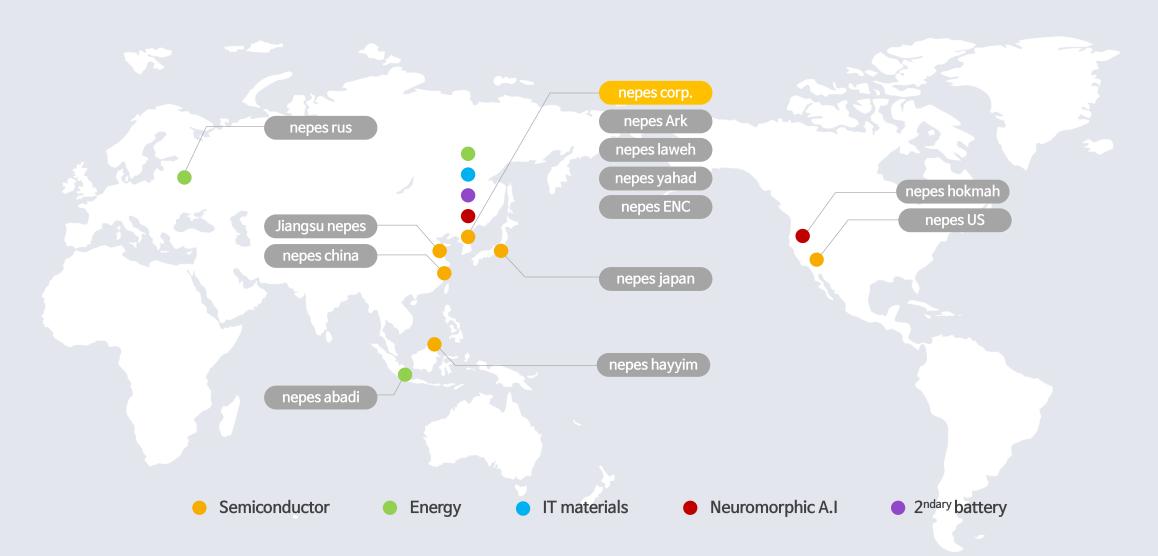








We will serve the earth with our technology and products



CORPORATE CULTURE



nepes continues to grow by creating performances through the development of unique corporate culture of its own











nepes consistently practices its own management philosophy



Life of service | Attitude of challenge | Heart of gratitude

MISSION

Helping Customers Succeed

Prestigious company

Model company

Service-oriented company



VISION

Global TOP-Tier

Innovation

Creation

Healthy Finance

CORE VALUE

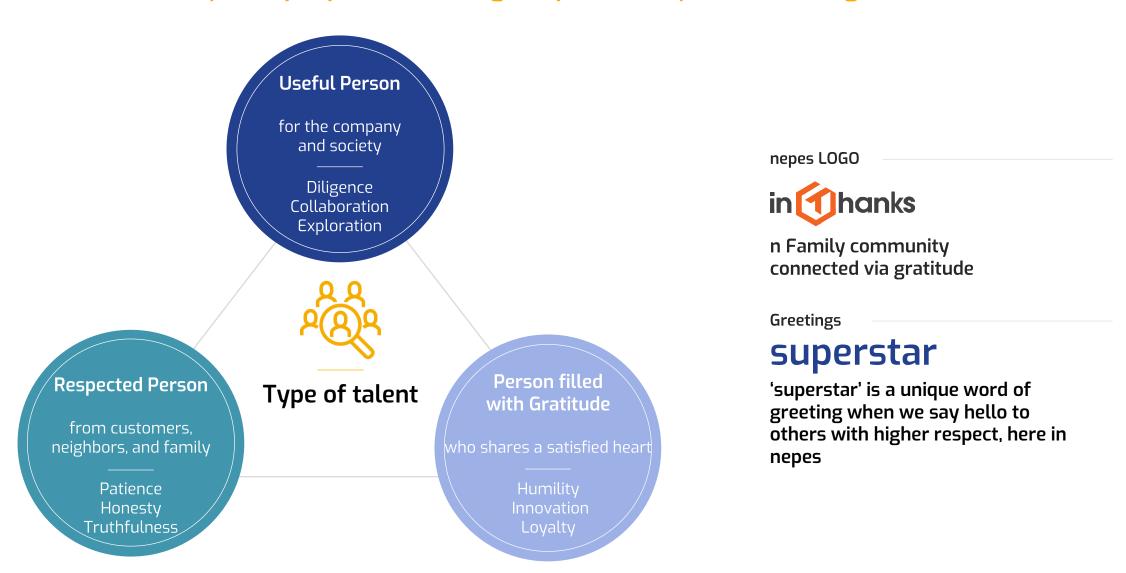
First-Class Corporate Culture

Togetherness · Humility · Gratitude





nepes is the community with people who have good personality to make things work



APPENDIX 3 Core Technology (Semiconductor)



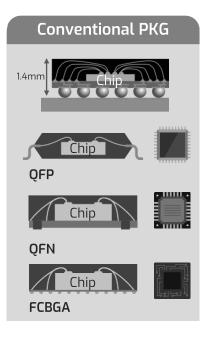
Market Trend

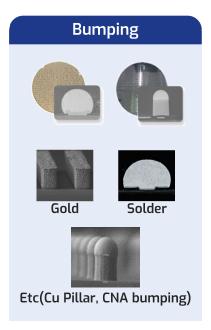
Smaller form factor

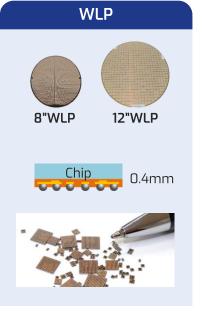
(Based on Wafer-Level Platform)

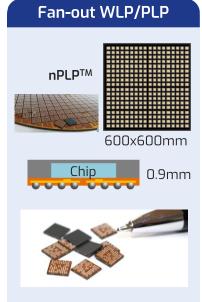
Highly integrated Wafer-Level System in Package

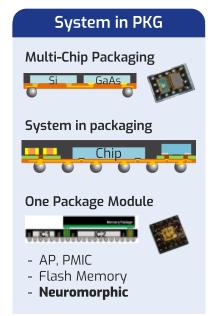
Tech. Roadmap











Position

nepes

End FAB Solution

(Bump, WLP, FOWLP, FOPLP, SiP, TEST)

Other OSAT

Conventional wire bonding packaging & Typical WLP technology

APPENDIX 4 Core Technology (Semiconductor)



